



Product Change Notification

102479 - 00

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Change Notification #: # 102479 - 00
Change Title: 132 lead Ceramic BGA Package (CBGA) 16 mil Solder Ball, Product Discontinuance, Revision to Original PCN 1141-03 to notify correction to Last Time Order Date.

Date of PCN Publication: Wednesday, May 08, 2002

Type of Change Notification:

Product Discontinuance

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Product Discontinuance Program Support Begins:	Aug 13, 2001
Product Discontinuance Demand to Local Intel Representative Due:	Dec 15, 2001
Last Product Discontinuance Order Date:	Aug 13, 2002
Last Product Discontinuance Shipment Date:	Feb 10, 2003

Description of Change to the Customer:

Revision to correct the Last Product Discontinuance Order Date From August 13, 2001 to August 13, 2002.

Original Text from PCN 1141-03

Revision 03 has been created to override revision 01 and 02. Revision 01 and 02 were submitted out of date sequence in the Forecasted Key Milestones and the PCN Revision History. All change data remains the same in revision 03 but milestone dates and PCN Revision History have been changed to reflect date sequence correction.

Intel-Giga is informing all customers of the Product Discontinuance of the 132 lead ceramic BGA (CBGA) product line. Please determine your remaining demand for the product and place your "Last Product Discontinuance Orders" in accordance with the Key Milestones listed above.

Customer Impact of Change and Recommended Action:

Revision to correct the Last Product Discontinuance Order Date From August 13, 2001 to August 13, 2002.

Original Text From PCN 1141-03

This revision is to notify customers of the Product Discontinuance of the 132 lead ceramic BGA package.

This change will impact customers that are currently using the 16 mil CBGA packages only and elect to use the 20 mil package. Stand-off height increases from 13 mils to 16 mils, with an increase of 3 mils in the overall package height. Samples are recommended for customers with solder pads smaller than 20 mils. Intel will continue to take orders for the 16 mil package in accordance with the Key milestones. Order codes for the 16 and 20 mil solder ball packages are listed in the following table.

Products Affected / Intel Ordering Codes:

Component Products Table

Pre-conversion Product Code	Pre-conversion Spec/ROM	Pre-conversion MM#	Post-conversion Product Code	Post-conversion Spec/ROM	Post-conversion MM#
HCGD16544EB		835469	HCGD16544EF		837345
HCGD16555BEB		835475	HCGD16555BEF		837403
HCGD16584EB		835478	HCGD16584EF		837347
HCGD16585EB		835479	HCGD16585EF		837348
HCGD16588EB		835480	HCGD16588EF		837349
HCGD16589EB		835481	HCGD16589EF		837350

Reference Documents / Attachments:

Document:

PCN 1141-03

Location #:

<http://fdb1.intel.com>

PCN Revision History:

Date of Revision:

May 08, 2002

Revision Number:

00

Reason:

Originally Published PCN